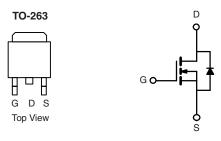


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Vishay Siliconix

# Automotive N-Channel 75 V (D-S) 175 °C MOSFET

PRODUCT SUMMARY				
V <sub>DS</sub> (V)	75			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 10 \text{ V}$	0.0048			
I <sub>D</sub> (A)	120			
Configuration	Single			



### **FEATURES**

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFET
- Package with Low Thermal Resistance
- AEC-Q101 Qualifiedd
- 100 % R<sub>q</sub> and UIS Tested
- Compliant to RoHS Directive 2002/95/EC



- 1	$\sim$	hor	nel	MAC	CE	⊏.

ORDERING INFORMATION	
Package	TO-263
Lead (Pb)-free and Halogen-free	SQM120N08-05-GE3

ABSOLUTE MAXIMUM RATINGS (T <sub>C</sub> = 25 °C, unless otherwise noted)						
PARAMETER		SYMBOL	LIMIT	UNIT		
Drain-Source Voltage		$V_{DS}$	75	V		
Gate-Source Voltage		V <sub>GS</sub>	± 20	V		
Continuous Drain Current	T <sub>C</sub> = 25 °C <sup>a</sup>	_	120			
	T <sub>C</sub> = 125 °C		106			
Continuous Source Current (Diode Conduction) <sup>a</sup>		Is	120	Α		
Pulsed Drain Current <sup>b</sup>		I <sub>DM</sub>	480			
Single Pulse Avalanche Current	nche Current L = 0.1 mH		66			
Single Pulse Avalanche Energy	L = 0.1 IIII	E <sub>AS</sub>	217	mJ		
Maximum Power Dissipation <sup>b</sup>	T <sub>C</sub> = 25 °C	р	375	W		
	T <sub>C</sub> = 125 °C	$P_{D}$	125	VV		
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to + 175	°C		

THERMAL RESISTANCE RATINGS						
PARAMETER		SYMBOL	LIMIT	UNIT		
Junction-to-Ambient	PCB Mount <sup>c</sup>	$R_{thJA}$	40	°C/W		
Junction-to-Case (Drain)		R <sub>thJC</sub>	0.4	C/VV		

#### Notes

- a. Package limited.
- b. Pulse test; pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2 %.
- c. When mounted on 1" square PCB (FR-4 material).
- d. Parametric verification ongoing.



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PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		75	-	-	V
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$		2.5	-	4.0	V
Gate-Source Leakage	I <sub>GSS</sub>	V <sub>DS</sub> =	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$		-	± 100	nA
		V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 75 V	-	-	1.0	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 75 V, T <sub>J</sub> = 125 °C	-	-	50	μΑ
		V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 75 V, T <sub>J</sub> = 175 °C	-	-	250	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>GS</sub> = 10 V	$V_{DS} \ge 5 V$	120	-	-	Α
Drain-Source On-State Resistance <sup>a</sup>		V <sub>GS</sub> = 10 V	I <sub>D</sub> = 30 A	-	0.0039	0.0048	Ω
	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 30 A, T <sub>J</sub> = 125 °C	-	-	0.0087	
		V <sub>GS</sub> = 10 V	I <sub>D</sub> = 30 A, T <sub>J</sub> = 175 °C	-	-	0.0110	
Forward Transconductance <sup>a, b</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 30 A		-	102	-	S
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>			-	8158	10 200	
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 V$	$V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$	-	865	1085	pF
Reverse Transfer Capacitance	C <sub>rss</sub>			-	567	710	
Total Gate Charge <sup>c</sup>	Qg			-	141	212	
Gate-Source Charge <sup>c</sup>	$Q_{gs}$	V <sub>GS</sub> = 10 V	$V_{DS} = 35 \text{ V}, I_D = 110 \text{ A}$	-	32.6	-	nC
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			-	39.1	-	
Gate Resistance	R <sub>g</sub>	f = 1 MHz		0.6	1.2	1.9	Ω
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>	$V_{DD}$ = 35 V, $R_L$ = 0.32 $\Omega$ $I_D$ $\cong$ 110 A, $V_{GEN}$ = 10 V, $R_g$ = 1 $\Omega$		-	19	29	
Rise Time <sup>c</sup>	t <sub>r</sub>			-	31	47	ns
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>			-	55	83	
Fall Time <sup>c</sup>	t <sub>f</sub>			-	15	23	
Source-Drain Diode Ratings and Chara	acteristics <sup>b</sup>						
Pulsed Current <sup>a</sup>	I <sub>SM</sub>			-	-	480	Α
Forward Voltage	$V_{SD}$	I <sub>F</sub> = 100 A, V <sub>GS</sub> = 0 V		_	0.9	1.5	V

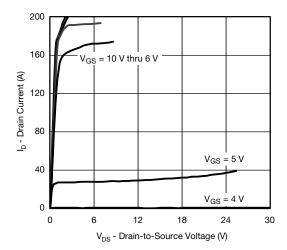
#### Notes

- a. Pulse test; pulse width  $\leq 300~\mu s,~duty~cycle \leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

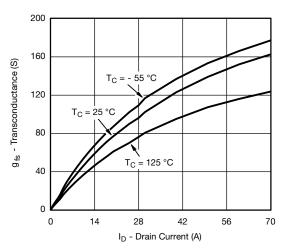
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



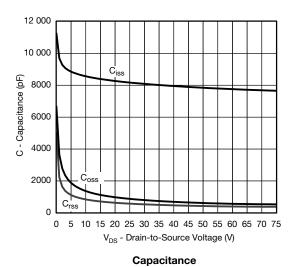
## **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)

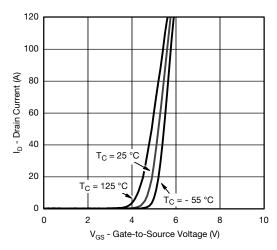


#### **Output Characteristics**

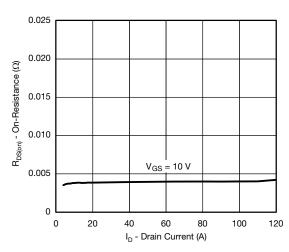


#### Transconductance

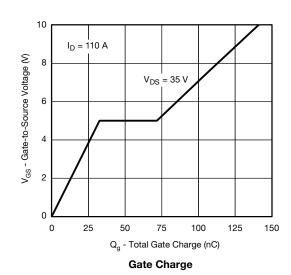




#### **Transfer Characteristics**

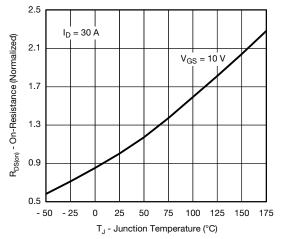


### On-Resistance vs. Drain Current

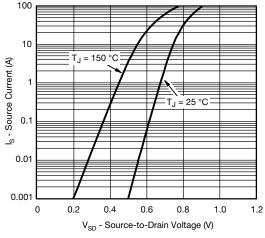




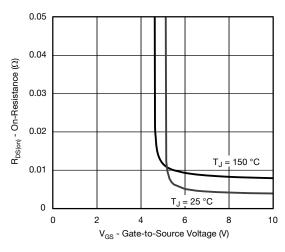
## **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



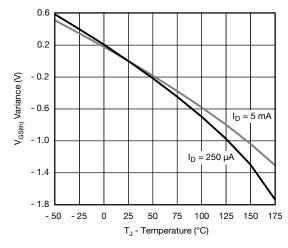
On-Resistance vs. Junction Temperature



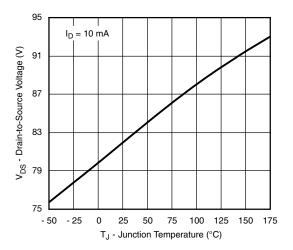
Source Drain Diode Forward Voltage



On-Resistance vs. Gate-to-Source Voltage



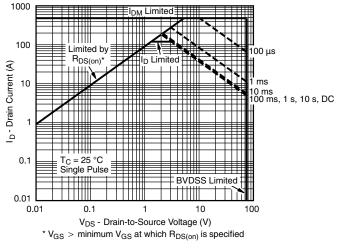
Threshold Voltage



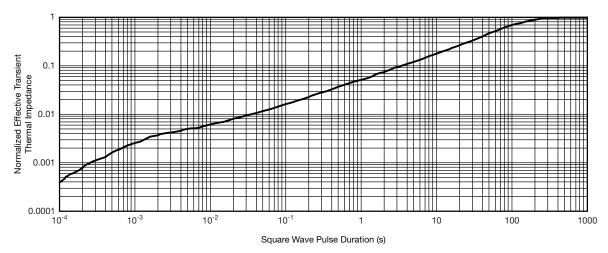
Drain Source Breakdown vs. Junction Temperature



## **THERMAL RATINGS** ( $T_A = 25$ °C, unless otherwise noted)



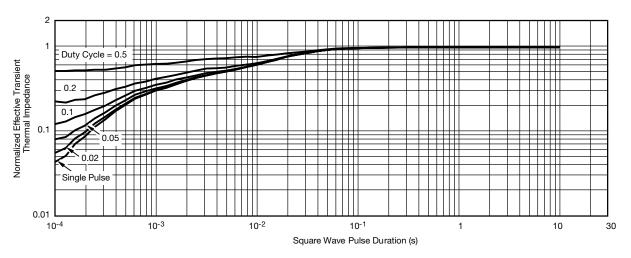
#### Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Ambient

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## THERMAL RATINGS (T<sub>A</sub> = 25 °C, unless otherwise noted)



#### Normalized Thermal Transient Impedance, Junction-to-Case

mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities

#### Note

- The characteristics shown in the two graphs
  - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)

can widely vary depending on actual application parameters and operating conditions.

- Normalized Transient Thermal Impedance Junction-to-Case (25 °C) are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part

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